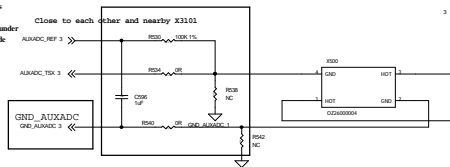
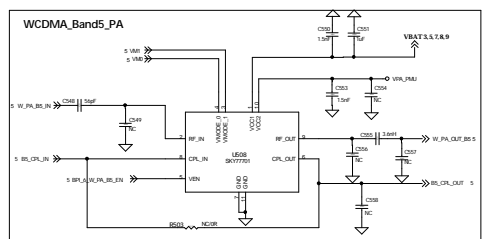
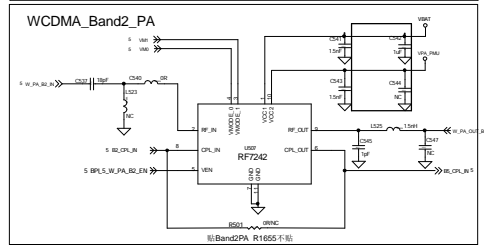
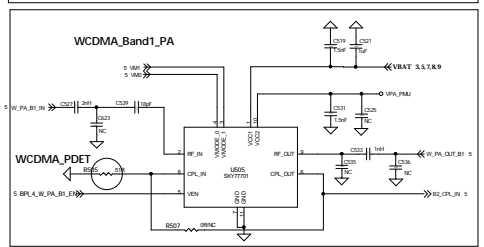
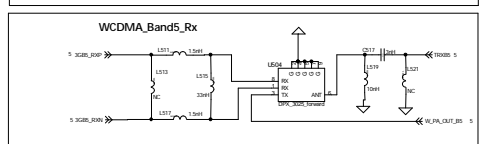
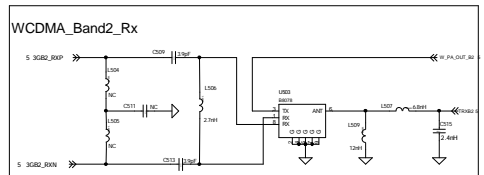
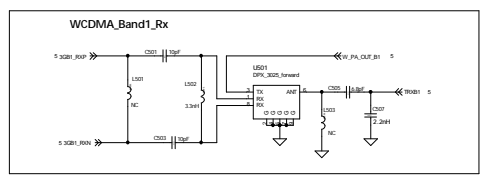


- 1.Route AUXADC_REF_REF/THERM_SENSE with full trace width
- 2.Route AUXADC_REF_REF/THERM_SENSE as differential trace with well GND shielding
- 3.Route AUXADC_GND with 16mil trace width under THERM_SENSE/AUXADC_REF trace to provide return current path.



Comment: THE FINAL GND to AVSS28_AUXADC first than connect to main GND



6

5

4

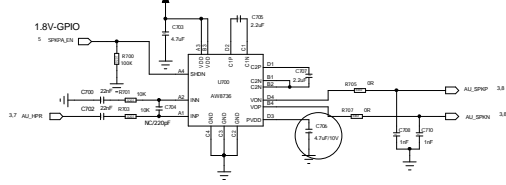
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2

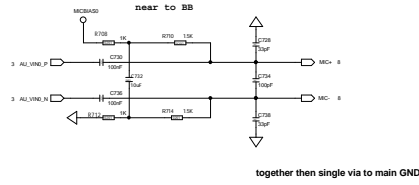
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REVISION RECORD			
LTR	ECO NO	APPROVED	DATE

AUDIO PA K

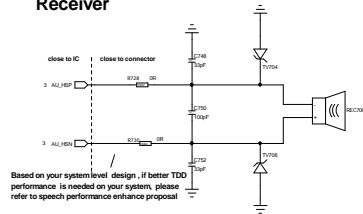


Handset Microphone 1



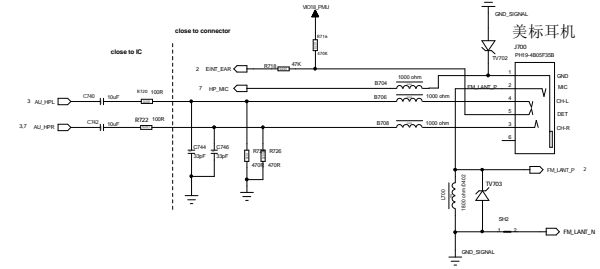
together then single via to main GND

Receiver



Based on your system level design, if better TDD performance is needed on your system, please refer to speech performance enhance proposal

Earphone Jack 3.5"



GND of C(4.7uF) and headset should tie together and single via to GND plane

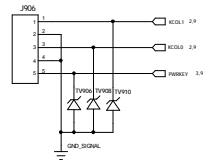
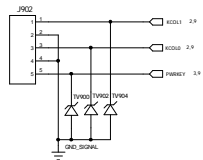
together then single via to main GND

COMPANY:				
TITLE:				
DRAWN:	DATED:	CODE:	SIZE:	DRAWING NO:
CHECKED:	DATED:	D		REV:
QUALITY CONTROL:	DATED:			
RELEASED:	DATED:	SCALE:	SHEET 2 10	

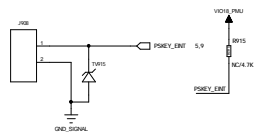
REVISION RECORD			
LTN	ECO NO	APPROVED	DATE

SIDE KEY

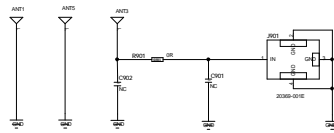
Volume Up : KCOL1 / GND
 Volume Down : KCOL0 / GND



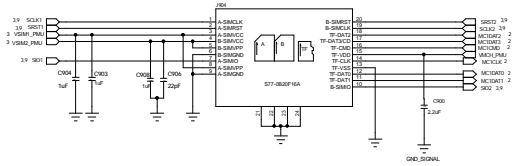
Power saving key



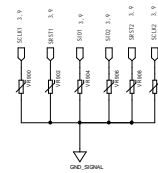
副板



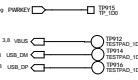
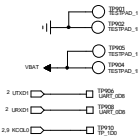
SIM1 SIM2 & TF



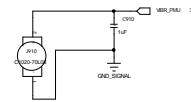
SIM ESD



TEST POINT



MOTOR



COMPANY:			
TITLE:			
DRAWN:	DATED:	CODE:	REV:
CHECKED:	DATED:	SIZE:	D
QUALITY CONTROL:	DATED:	DRAWING NO:	
RELEASED:	DATED:	SCALE:	SHEET 10